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For Immediate Release

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Seika Machinery to Host SMI 2026 Webinar Series Session 2 on PCB Slicing Methods and Low-Stress Separation

TORRANCE, CA — July 2026 — Seika Machinery, Inc., a leading provider of advanced machinery, materials and engineering services, will present the second session of its SMI 2026 Summer Webinar Series on Wednesday, July 8 at 10:00 a.m. PDT, focusing on how PCB slicing methods impact board quality, component reliability, and overall manufacturing consistency.

Webinar Registration:
Register for SMI 2026 Webinar Series Session 2

Titled “PCB Slicing Methods: Comparing Stress, Edge Quality and Process Performance,” the session takes a practical look at how different separation techniques influence mechanical stress and finished board quality, and why those differences matter in real-world production.

The webinar will cover commonly used depaneling approaches, including hand breaking, pliers, guillotine cutters, and standard PCB slicers. It will compare the strengths and limitations of each method, along with strain gauge data that highlights the differences in stress introduced during manual separation. Real examples of edge damage and component-related defects will also be reviewed to show what can happen when boards are separated without controlled processes.

A portion of the session will focus on Sayaka PCB slicing systems, spanning manual, semi-automatic, and fully automated platforms. Presenters will discuss how low-stress, controlled separation helps protect components, improve edge quality, and deliver more repeatable results across different production environments.

For manufacturers evaluating alternatives to manual depaneling or looking to improve throughput with automation, the session is designed to provide straightforward guidance on selecting the right method based on board design, production volume, and reliability requirements.

The webinar is complimentary, but advance registration is required.

Date: Wednesday, July 8, 2026
Time: 10:00 a.m. PDT

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About Seika Machinery, Inc.
Seika Machinery, Inc. (SMI) is a subsidiary of Seika Corporation, Japan and member of the Mitsubishi Global Group. SMI provides electronics manufacturers with advanced machinery, superior materials and engineering services.